

BiCMOS Advanced Phase Shift PWM Controller

FEATURES

- Programmable Output Turn-on Delay
- Adaptive Delay Set
- Bidirectional Oscillator Synchronization
- Capability for Voltage Mode or Current Mode Control
- Programmable Soft Start/Soft Stop and Chip Disable via a Single Pin
- 0% to 100% Duty Cycle Control
- 7MHz Error Amplifier
- Operation to 1MHz
- Low Active Current Consumption (5mA Typical @ 500kHz)
- Very Low Current Consumption During Undervoltage Lock-out (150µA typical)

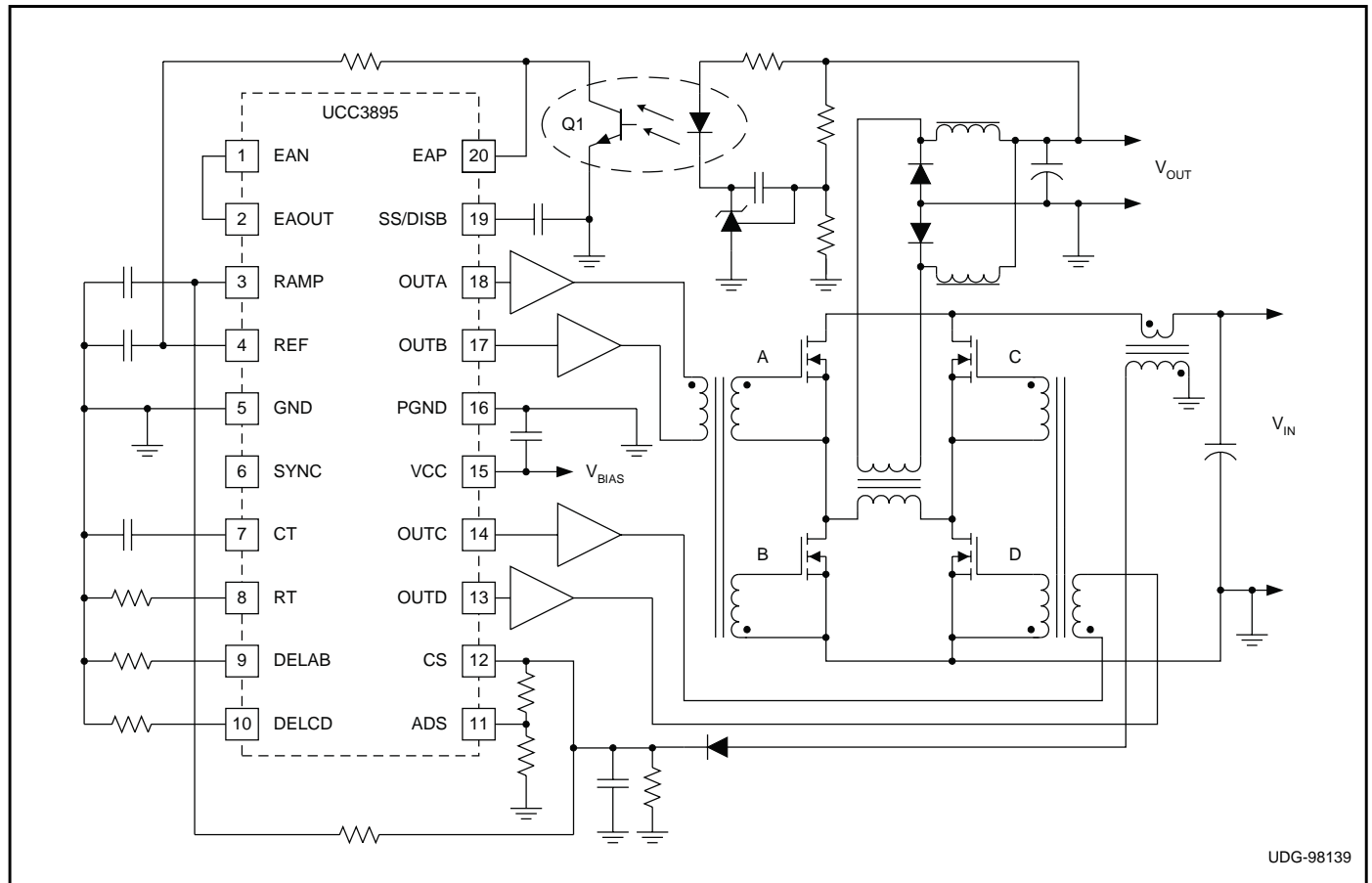
DESCRIPTION

The UCC3895 is a phase shift PWM controller that implements control of a full-bridge power stage by phase shifting the switching of one half-bridge with respect to the other. It allows constant frequency pulse-width modulation in conjunction with resonant zero-voltage switching to provide high efficiency at high frequencies. The part can be used either as a voltage mode or current mode controller.

While the UCC3895 maintains the functionality of the UC3875/6/7/8 family and UC3879, it improves on that controller family with additional features such as enhanced control logic, adaptive delay set, and shutdown capability. Since it is built in BCDMOS, it operates with dramatically less supply current than its bipolar counterparts. The UCC3895 can operate with a maximum clock frequency of 1MHz.

The UCC3895 and UCC2895 are offered in the 20 pin SOIC (DW) package, 20 pin PDIP (N) package, 20 pin TSSOP (PW) package, and 20 pin PLCC (Q). The UCC1895 is offered in the 20 pin CDIP (J) package, and 20 pin CLCC package (L).

SIMPLIFIED APPLICATION DIAGRAM



UDG-98139

ELECTRICAL CHARACTERISTICS: Unless otherwise specified, VDD=12V, RT=82kΩ, CT=220pF, RDELAB=10kΩ, RDELCD=10kΩ, CREF=0.1μF, CVDD=1.0μF, no load at outputs. TA = TJ. TA = 0°C to 70°C for UCC3895x, -40°C to +85°C for UCC2895x, and -55°C to +125°C for UCC1895x.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Voltage Reference Section					
Output Voltage	TJ = 25°C	4.94	5.00	5.06	V
	10V < VDD < 17.5V, 0mA < IREF < 5mA, Temperature	4.85	5	5.15	V
Short Circuit Current	REF = 0V, TJ = 25°C	10	20		mA
Error Amplifier Section					
Common Mode Input Voltage Range		-0.1		3.6	V
Offset Voltage		-7		7	mV
Input Bias Current (EAP, EAN)		-1		1	μA
EAOUT VOH	EAP-EAN = 500mV, IEAOUT= -0.5mA	4.0	4.5	5.0	V
EAOUT VOL	EAP-EAN = -500mV, IEAOUT= 0.5mA	0	0.2	0.4	V
EAOUT Source Current	EAP-EAN = 500mV, EAOUT= 2.5V	1.0	1.5		mA
EAOUT Sink Current	EAP-EAN = -500mV, EAOUT= 2.5V, (Note 4)	2.5	4.5		mA
Open Loop DC Gain		75	85		dB
Unity Gain Bandwidth	(Note 3)	5.0	7.0		MHz
Slew Rate	EAN from 1V to 0V, EAP = 500mV, EAOUT from 0.5V to 3.0V, (Note 3)	1.5	2.2		V/μs
No Load Comparator Turn-Off Threshold		0.45	0.50	0.55	V
No Load Comparator Turn-On Threshold		0.55	0.60	0.69	V
No Load Comparator Hysteresis		0.035	0.100	0.165	V
Oscillator Section					
Frequency	TJ = 25°C	473	500	527	kHz
Total Variation	Line, Temperature (Note 3)		2.5	5	%
SYNC VIH		2.05	2.10	2.25	V
SYNC VIL		1.85	1.90	1.95	V
SYNC VOH	ISYNC = -400μA, CT = 2.6V	4.1	4.5	5.0	V
SYNC VOL	ISYNC = 100μA, CT = 0V	0.0	0.5	1.0	V
SYNC Output Pulse Width	SYNC Load = 3.9kΩ and 30pF in parallel		85	135	ns
RT Voltage		2.9	3	3.1	V
CT Peak Voltage		2.25	2.35	2.50	V
CT Valley Voltage	UCC2895, UCC3895	0.0	0.2	0.4	V
CT Valley Voltage	UCC1895	0.0	0.2	0.6	V
PWM Comparator Section					
EAOUT to RAMP Input Offset Voltage	RAMP = 0V, DELAB = DELCD = REF	0.72	0.85	1.05	V
Minimum Phase Shift (OUTA to OUTC, OUTB to OUTD)	RAMP = 0V, EAOUT = 650mV (Note 1)	0.00	0.85	1.40	%
RAMP to OUTC/OUTD Delay	RAMP from 0V to 2.5V, EAOUT = 1.2V, DELAB = DELCD = REF (Note 2)		70	120	ns
RAMP Bias Current	RAMP < 5V, CT < 2.2V	-5		5	μA
RAMP Sink Current	RAMP = 5V, CT < 2.6V	12	19		mA
Current Sense Section					
CS Bias Current	0 < CS, 2.5V, 0 < ADS < 2.5V	-4.5		20	μA
Peak Current Threshold		1.90	2.00	2.10	V
Overcurrent Threshold		2.4	2.5	2.6	V
CS to Output Delay	CS from 0 to 2.3V, DELAB = DELCD = REF		75	110	ns

ELECTRICAL CHARACTERISTICS: Unless otherwise specified, VDD=12V, RT=82kΩ, CT=220pF, RDELAB=10kΩ, RDELCD=10kΩ, CREF=0.1μF, CVDD=1.0μF, no load at outputs. TA = TJ. TA = 0°C to 70°C for UCC3895x, -40°C to +85°C for UCC2895x, and -55°C to +125°C for UCC1895x.

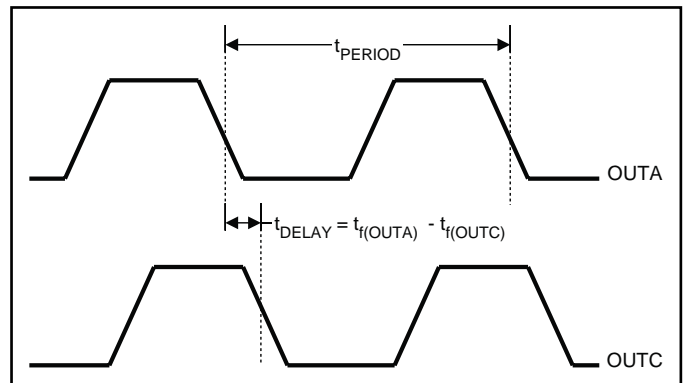
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Soft Start/Shutdown Section					
Soft Start Source Current	SS/DISB = 3.0V, CS < 1.9V	-40	-35	-30	μA
Soft Start Sink Current	SS/DISB = 3.0V, CS > 2.6V	325	350	375	μA
Soft Start/Disable Comparator Threshold		0.44	0.50	0.56	V
Delay Set Section					
DELAB/DELCD Output Voltage	ADS = CS = 0V	0.45	0.50	0.55	V
	ADS = 0V, CS = 2.0V	1.9	2.0	2.1	V
Output Delay	ADS = CS = 0V (Notes 2 and 3)	450	525	600	ns
ADS Bias Current	0V < ADS < 2.5V, 0V < CS < 2.5V	-20		20	μA
Output Section					
VOH (all outputs)	IOUT = -10mA, VDD to Output		250	400	mV
VOL (all outputs)	IOUT = 10mA		150	250	mV
Rise Time	CLOAD = 100pF, (Note 3)		20	35	ns
Fall Time	CLOAD = 100pF, (Note 3)		20	35	ns

Note 1: Minimum phase shift is defined as followed:

$$\Phi = 200 \cdot \frac{t_{f(OUTA)} - t_{f(OUTC)}}{t_{PERIOD}} \text{ Or}$$

$$\Phi = 200 \cdot \frac{t_{f(OUTB)} - t_{f(OUTD)}}{t_{PERIOD}} \text{ where}$$

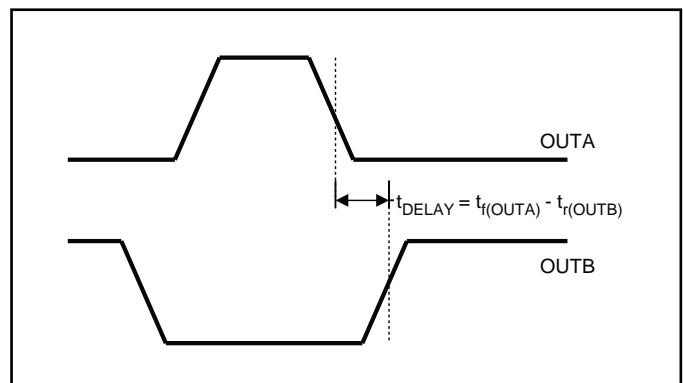
t_{f(OUTA)} = falling edge of OUTA signal
t_{f(OUTB)} = falling edge of OUTB signal
t_{f(OUTC)} = falling edge of OUTC signal
t_{f(OUTD)} = falling edge of OUTD signal
t_{PERIOD} = period of OUTA or OUTB signal



Same applies to OUTB and OUTD

Note 2. Output delay is measured between OUTA/OUTB or OUTC/OUTD. Output delay is defined as shown below, where:

t_{f(OUTA)} = falling edge of OUTA signal
t_{r(OUTB)} = rising edge of OUTB signal



Same applies to OUTC and OUTD

Note 3: Ensured by design. Not 100% tested in production.

Note 4: For UCC1895, MIN limit is 2.2 mA at -55°C

PIN DESCRIPTIONS

ADS: Adaptive Delay Set. This function sets the ratio between the maximum and minimum programmed output delay dead time. When the ADS pin is directly connected to the CS pin, no delay modulation occurs. The maximum delay modulation occurs when ADS is grounded. In this case, delay time is four times longer when CS = 0 than when CS = 2.0V (the Peak Current threshold), ADS changes the output voltage on the delay pins DELAB and DELCD by the following formula:

$$V_{\text{DEL}} = [0.75 \cdot (V_{\text{CS}} - V_{\text{ADS}})] + 0.5\text{V}$$

where V_{CS} and V_{ADS} are in Volts. ADS must be limited to between 0V and 2.5V and must be less than or equal to CS. DELAB and DELCD also will be clamped to a minimum of 0.5V.

EAOUT: Error Amplifier Output. It is also connected internally to the non-inverting input of the PWM comparator and the no-load comparator. EAOUT is internally clamped to the soft start voltage. The no-load comparator shuts down the output stages when EAOUT falls below 500mV, and allows the outputs to turn-on again when EAOUT rises above 600mV.

CT: Oscillator Timing Capacitor. (Refer to Fig. 1, Oscillator Block Diagram) The UCC3895's oscillator charges CT via a programmed current. The waveform on CT is a sawtooth, with a peak voltage of 2.35V. The approximate oscillator period is calculated by the following formula:

$$t_{\text{OSC}} = \frac{5 \cdot R_{\text{T}} \cdot C_{\text{T}}}{48} + 120\text{ns}$$

where C_{T} is in Farads, and R_{T} is in Ohms and t_{OSC} is in seconds. C_{T} can range from 100pF to 880pF. Please note that a large C_{T} and a small R_{T} combination will result in extended fall times on the C_{T} waveform. The increased fall time will increase the SYNC pulse width, hence limiting the maximum phase shift between OUTA, OUTB and OUTC, OUTD outputs, which limits the maximum duty cycle of the converter.

CS: Current Sense. This is the inverting input of the Current Sense comparator and the non-inverting input of the Over-current comparator, and the ADS amplifier. The current sense signal is used for cycle-by-cycle current limiting in peak current mode control, and for overcurrent protection in all cases with a secondary threshold for output shutdown. An output disable initiated by an overcurrent fault also results in a restart cycle, called "soft stop", with full soft start.

DELAB, DELCD: Delay Programming Between Complementary Outputs. DELAB programs the dead time between switching of OUTA and OUTB, and DELCD programs the dead time between OUTC and OUTD. This delay is introduced between complementary outputs in the same leg of the external bridge. The UCC3895 allows the user to select the delay, in which the resonant switching of the external power stages takes place. Separate delays are provided for the two half-bridges to accommodate differences in resonant capacitor charging currents. The delay in each stage is set according to the following formula:

$$t_{\text{DELAY}} = \frac{(25 \cdot 10^{-12}) \cdot R_{\text{DEL}}}{V_{\text{DEL}}} + 25\text{ns}$$

where V_{DEL} is in Volts, and R_{DEL} is in Ohms and t_{DELAY} is in seconds. DELAB and DELCD can source about 1mA maximum. Choose the delay resistors so that this maximum is not exceeded. Programmable output delay can be defeated by tying DELAB and/or DELCD to REF. For an optimum performance keep stray capacitance on these pins at <10pF.

EAP: The non-inverting input to the error amplifier.

EAN: The inverting input to the error amplifier.

GND: Chip ground for all circuits except the output stages.

OUTA, OUTB, OUTC, OUTD: The 4 outputs are 100mA complementary MOS drivers, and are optimized to drive FET driver circuits. OUTA and OUTB are fully complementary, (assuming no programmed delay). They operate near 50% duty cycle and one-half the oscillating frequency. OUTA and OUTB are intended to drive one half-bridge circuit in an external power stage. OUTC and OUTD will drive the other half-bridge and will have the same characteristics as OUTA and OUTB. OUTC is phase shifted with respect to OUTA, and OUTD is phase shifted with respect to OUTB. Note that changing the phase relationship of OUTC and OUTD with respect to OUTA and OUTB requires other than the nominal 50% duty ratio on OUTC and OUTD during those transients.

PGND: Output Stage Ground. To keep output switching noise from critical analog circuits, the UCC3895 has 2 different ground connections. PGND is the ground connection for the high-current output stages. Both GND and PGND must be electrically tied together closely near the IC. Also, since PGND carries high current, board traces must be low impedance.

PIN DESCRIPTIONS (cont.)

RAMP: The Inverting Input of the PWM Comparator. This pin receives either the CT waveform in voltage and average current mode controls, or the current signal (plus slope compensation) in peak current mode control. An internal discharge transistor is provided on RAMP, which is triggered during the oscillator dead time.

RT: Oscillator Timing Resistor. (Refer to Fig. 1, Oscillator Block Diagram) The oscillator in the UCC3895 operates by charging an external timing capacitor, CT, with a fixed current programmed by R_T . R_T current is calculated as follows:

$$I_{RT} = \frac{3.0V}{R_T}$$

where R_T is in Ohms and I_{RT} is in Amperes. R_T can range from 40k Ω to 120k Ω . Soft start charging and discharging current are also programmed by I_{RT} .

SS/DISB: Soft Start/Disable. This pin combines the two independent functions.

Disable Mode: A rapid shutdown of the chip is accomplished by any one of the following: externally forcing SS/DISB below 0.5V, externally forcing REF below 4V, V_{DD} dropping below the UNLO threshold, or an overcurrent fault is sensed ($CS = 2.5V$).

In the case of REF being pulled below 4V or an UVLO condition, SS/DISB is actively pulled to ground via an internal MOSFET switch. If an overcurrent is sensed, SS/DISB will sink a current of $(10 \cdot I_{RT})$ until SS/DISB falls below 0.5V.

Note that if SS/DISB is externally forced below 0.5V the pin will start to source current equal to I_{RT} . Also note that the only time the part switches into the low I_{DD} current mode is when the part is in undervoltage lockout.

APPLICATION INFORMATION

Programming DELAB, DELCD, and the Adaptive Delay Set

The UCC3895 allows the user to set the delay between switch commands within each leg of the full bridge power circuit according to the following formula from the data sheet:

$$t_{DELAY} = \frac{(25 \cdot 10^{-12}) \cdot R_{DEL}}{V_{DEL}} + 25nsec$$

For this equation V_{DEL} is determined in conjunction with the desire to utilize (or not utilize) the adaptive delay set feature from the following formula:

$$V_{DEL} = [0.75 \cdot (V_{CS} - V_{ADS})] + 0.5V$$

The following diagram illustrates the resistors needed to program the delay periods and the adaptive delay set function.

Soft Start Mode: After a fault or disable condition has passed, V_{DD} is above the start threshold, and/or SS/DISB falls below 0.5V during a soft stop, SS/DISB will switch to a soft start mode. The pin will now source current, equal to I_{RT} . A user-selected capacitor on SS/DISB determines the soft start (and soft-start) time. In addition, a resistor in parallel with the capacitor may be used, limiting the maximum voltage on SS/DISB. Note that SS/DISB will actively clamp the EAOUT pin voltage to approximately the SS/DISB pin voltage during both soft start, soft stop, and disable conditions.

SYNC: Oscillator Synchronization. (Refer to Fig. 1, Oscillator Block Diagram) This pin is bidirectional. When used as an output, SYNC can be used as a clock, which is the same as the chip's internal clock. When used as an input, SYNC will override the chip's internal oscillator and act as its clock signal. This bidirectional feature allows synchronization of multiple power supplies. The SYNC signal will also internally discharge the CT capacitor and any filter capacitors that are present on the RAMP pin. The internal SYNC circuitry is level sensitive, with an input low threshold of 1.9V, and an input high threshold of 2.1V. A resistor as small as 3.9k Ω may be tied between SYNC and GND to reduce the sync pulse width.

VDD: Power Supply. V_{DD} must be bypassed with a minimum of a 1.0 μ F low ESR, low ESL capacitor to ground.

REF: 5V, $\pm 1.2\%$ voltage reference. The reference supplies power to internal circuitry, and can also supply up to 5mA to external loads. The reference is shut down during undervoltage lock-out but is operational during all other disable modes. For best performance, bypass with a 0.1 μ F low ESR, low ESL capacitor to ground.

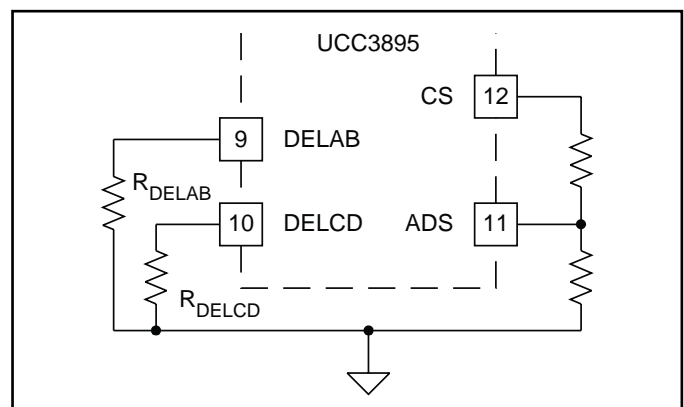


Figure 1. Resistors needed in programming.

APPLICATION INFORMATION (CONT.)

The Adaptive Delay Set feature (ADS) allows the user to vary the delay times between switch commands within each of the converter’s two legs. The delay time modulation is implemented by connecting ADS (pin 11) to CS, GND, or a resistive divider from CS to GND to set V_{ADS} . From the equation for V_{DEL} above, if ADS is tied to GND then V_{DEL} rises in direct proportion to V_{CS} , causing a decrease in t_{DELAY} as the load increases. In this condition the maximum value of V_{DEL} is 2V. If ADS is connected to a resistive divider between CS and GND the term $(V_{CS}-V_{DS})$ becomes smaller, reducing the level of V_{DEL} . This will decrease the amount of delay modulation. In the limit of ADS tied to CS, $V_{DEL}=0.5V$ and no delay modulation occurs. In the case with maximum delay modulation (ADS=GND), when the circuit goes from light load to heavy load the variation of V_{DEL} is from 0.5V to 2V. This causes the delay times to vary by a 4:1 ratio as the load is changed.

The ability to program an adaptive delay is a desirable feature because the optimum delay time is a function of the current flowing in the primary winding of the transformer, and can change by a factor of 10:1 or more as circuit loading changes. Reference [1] delves into the many interrelated factors for choosing the optimum delay times for the most efficient power conversion, and illustrates an external circuit to enable adaptive delay set us-

ing the UC3879. Implementing this adaptive feature is simplified in the UCC3895 controller, giving the user the ability to tailor the delay times to suit a particular application with a minimum of external parts.

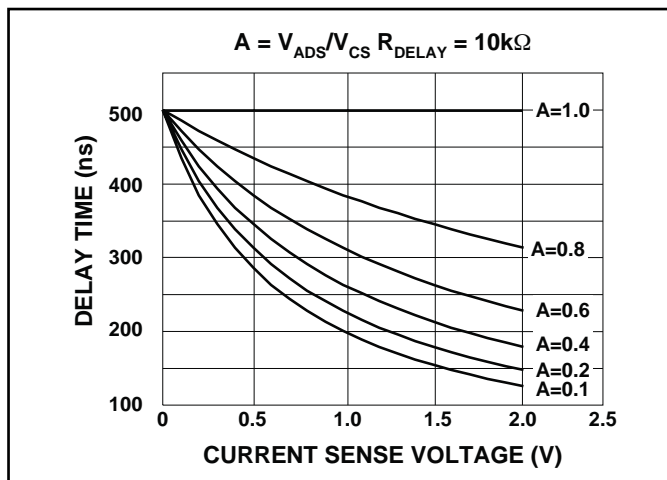


Figure 2. Resistors needed for programming.

[1] L. Balogh, “Design Review: 100W, 400kHz, DC/DC Converter With Current Doubler Synchronous Rectification Achieves 92% Efficiency,” Unitrode Power Supply Design Seminar Manual, Unitrode Corporation, 1996, Topic 2.

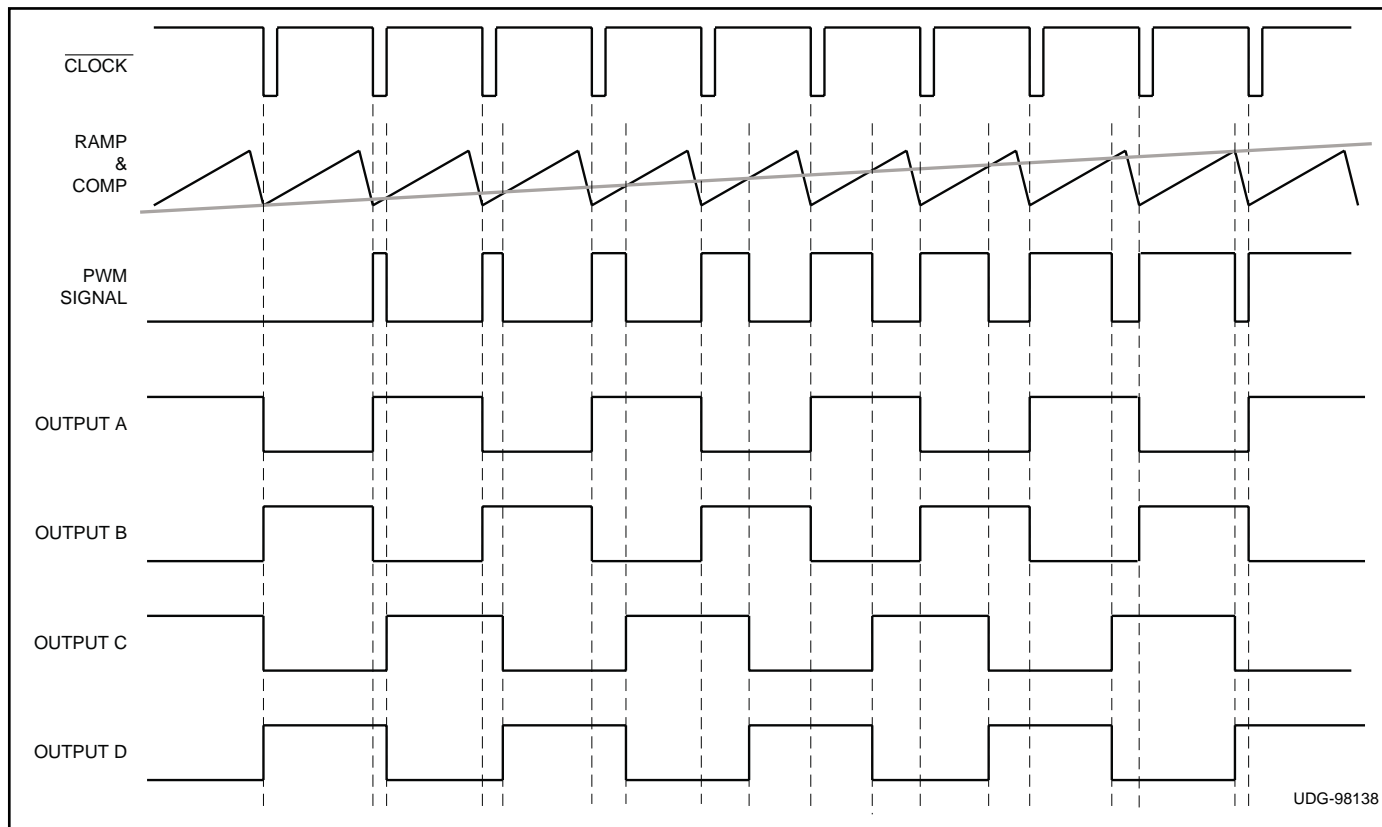


Figure 3. UCC3895 timing diagram (no output delay shown).

APPLICATION INFORMATION (cont.)

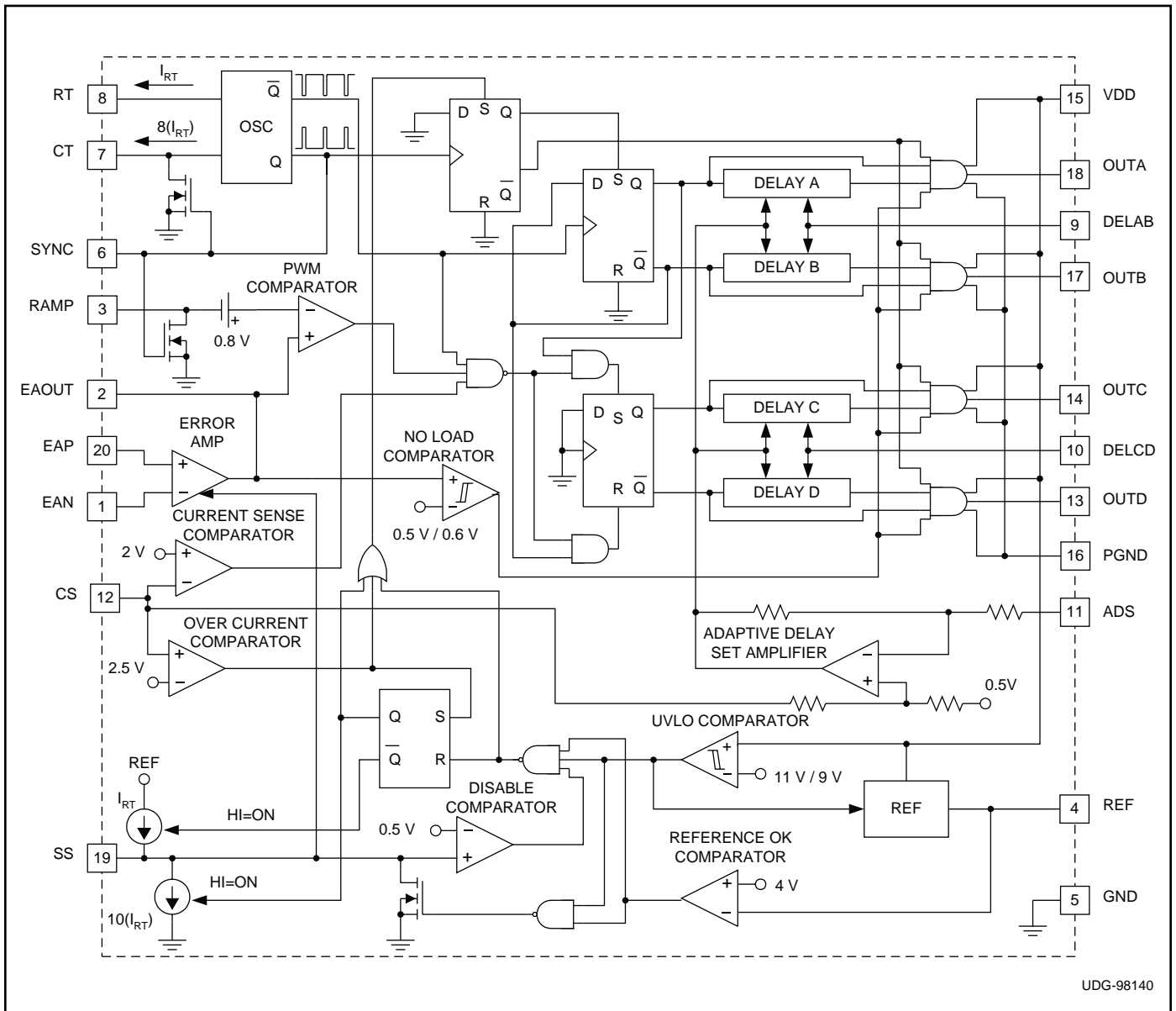


Figure 4. Block diagram.

CIRCUIT DESCRIPTION

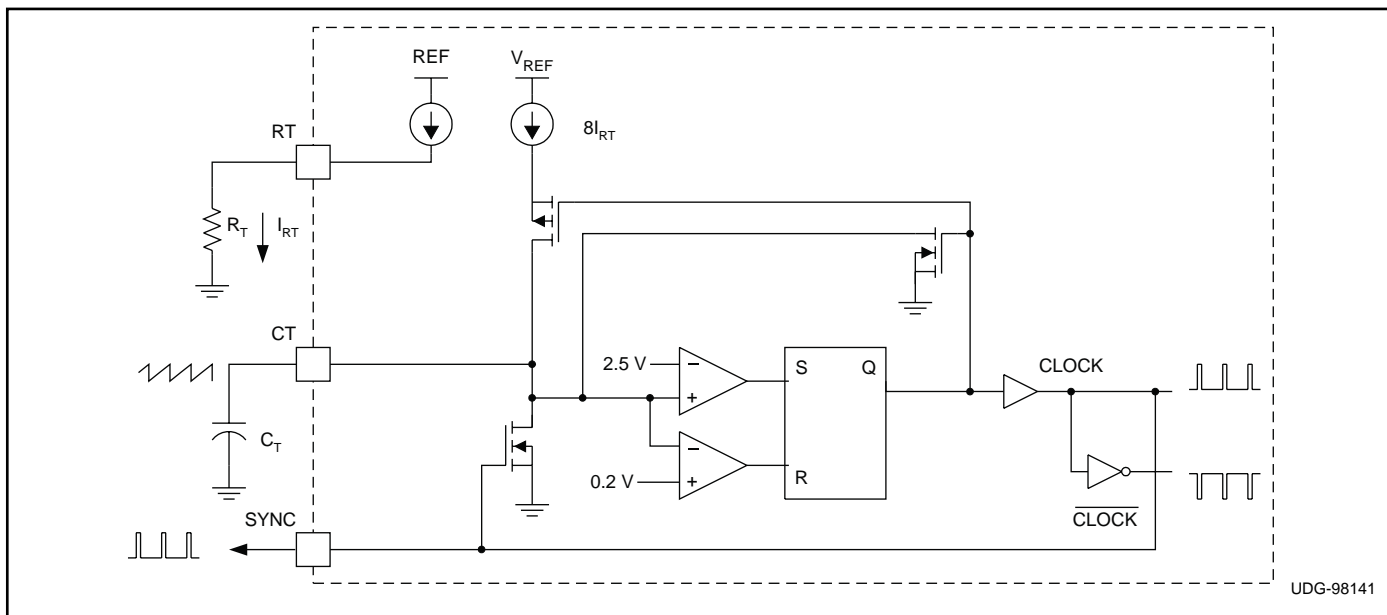


Figure 5. Oscillator block diagram.

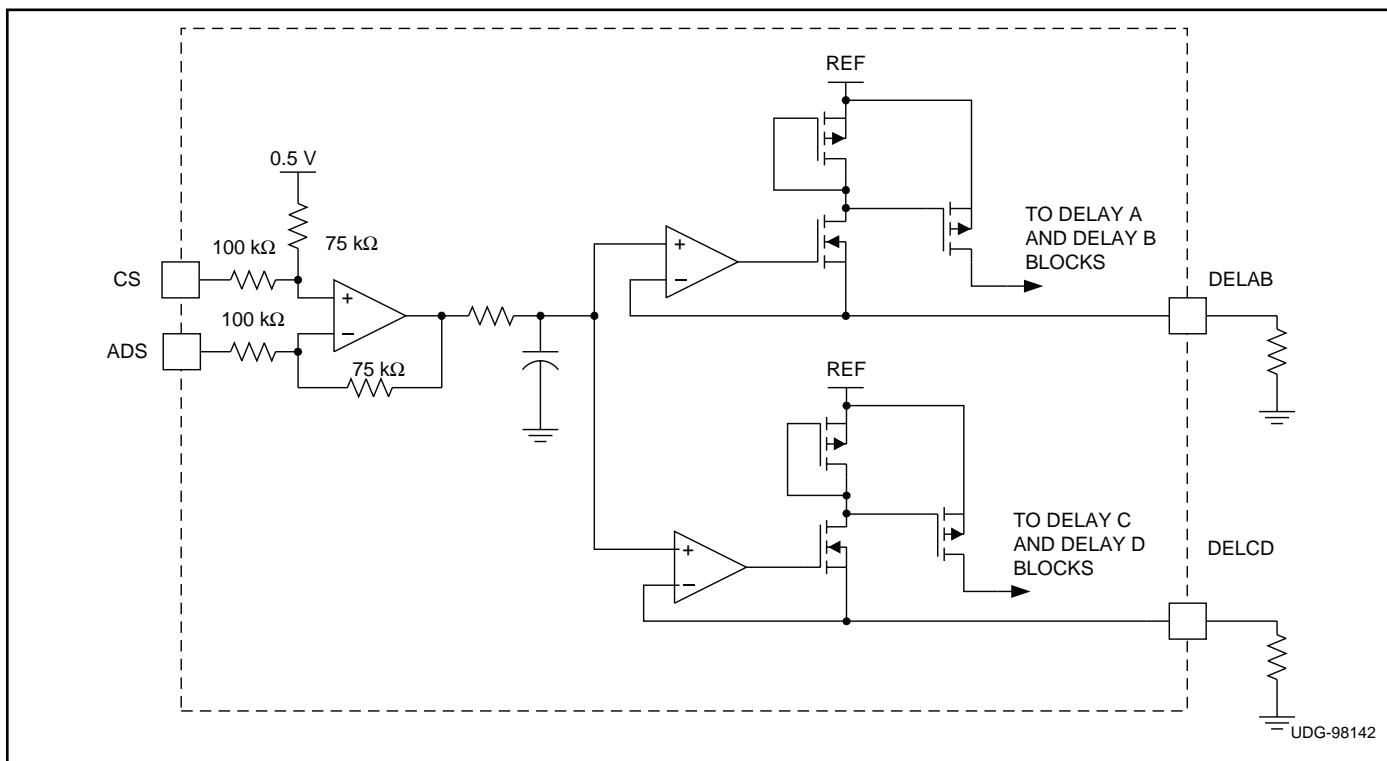


Figure 6. Adaptive delay set block diagram.

CIRCUIT DESCRIPTION (cont.)

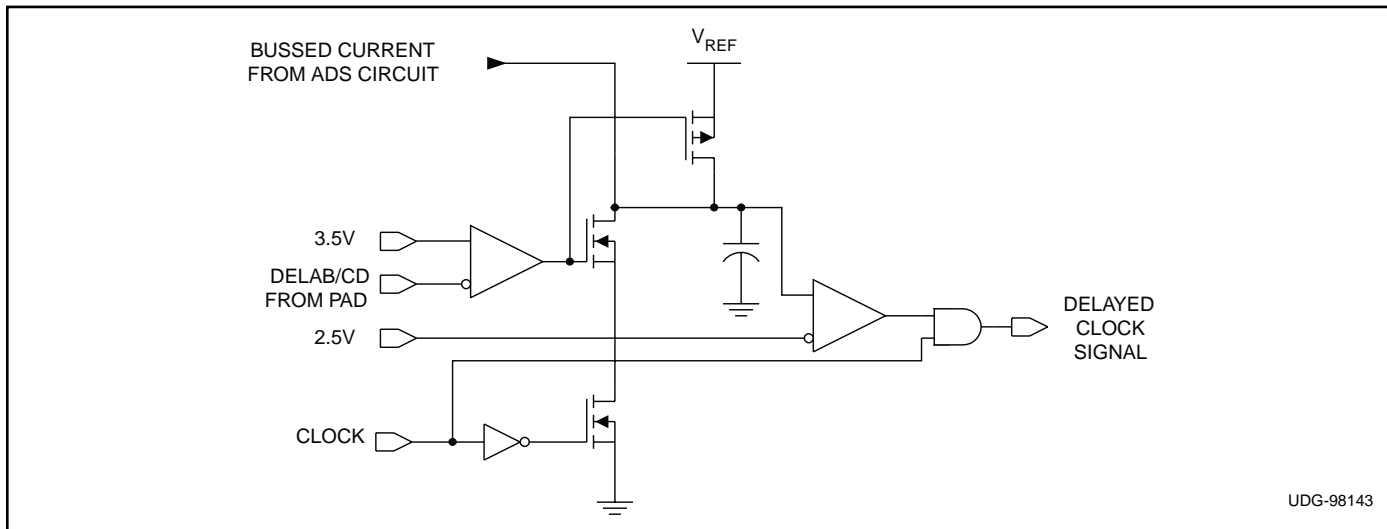


Figure 7. Delay block diagram (one delay block per output).

TYPICAL CHARACTERISTIC

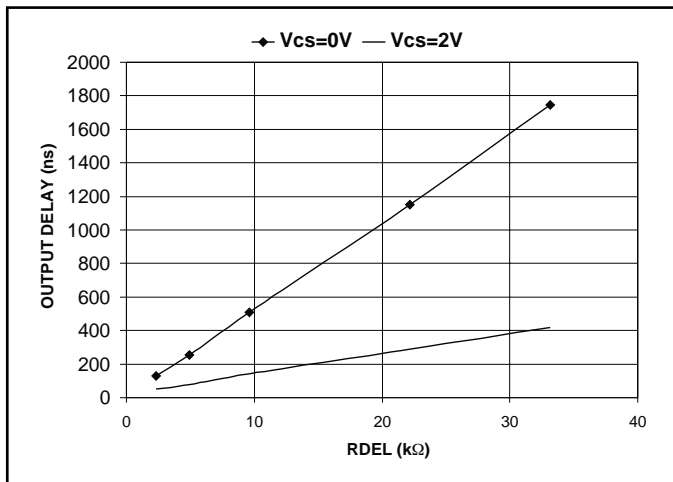


Figure 8. Delay programming: characterizes the output delay between A/B, C/D.

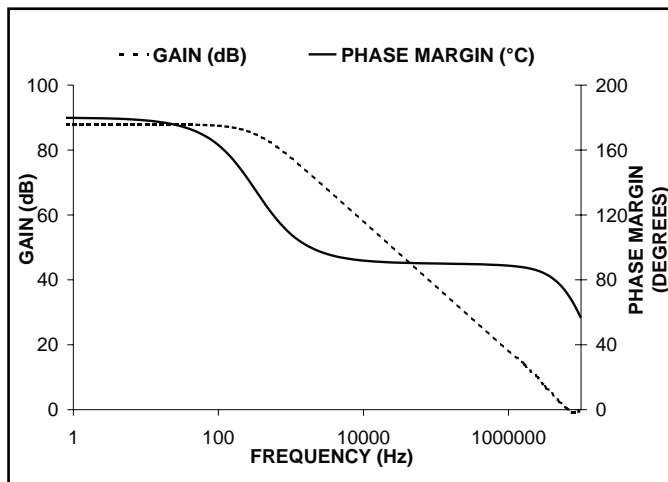


Figure 10. Error amplifier gain/phase margin.

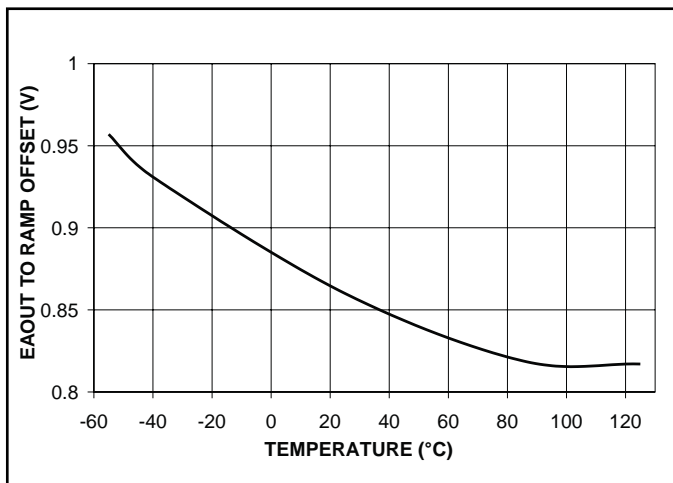


Figure 9. EAOUT to RAMP offset over temperature.

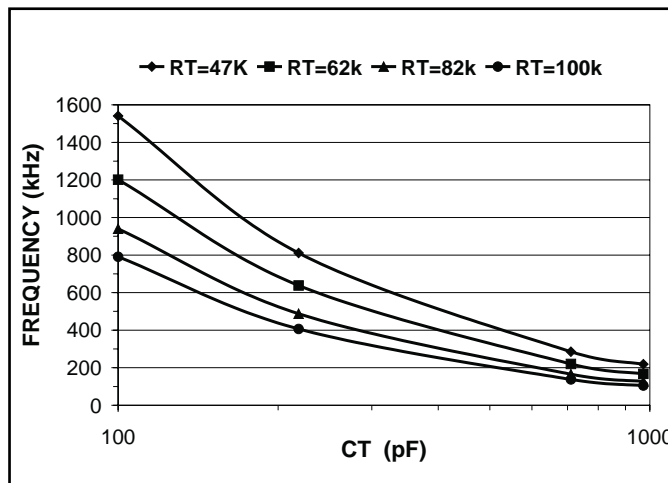


Figure 11. Frequency vs. RT/CT (oscillator frequency).

TYPICAL CHARACTERISTIC (cont.)

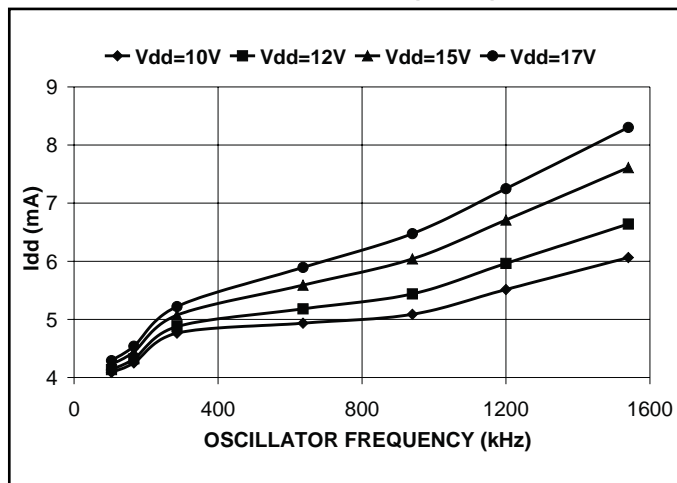


Figure 12. I_{DD} vs. V_{DD} / oscillator frequency (no output loading).

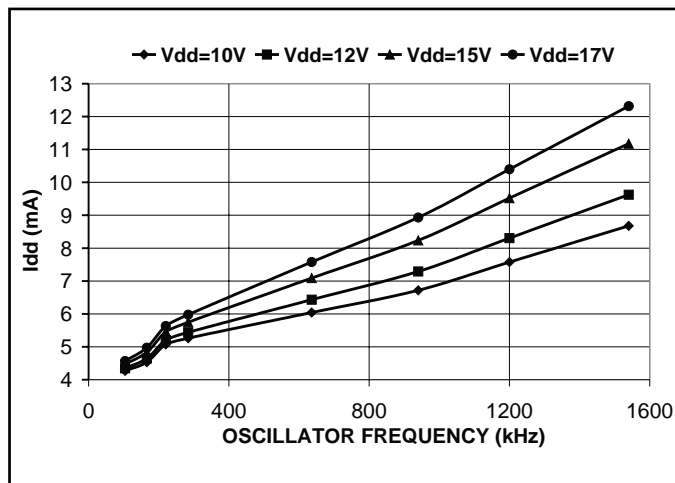


Figure 13. I_{DD} vs. V_{DD} / oscillator frequency (with 0.1nF output loads).

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UCC1895J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	Level-NC-NC-NC
UCC1895L	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	Level-NC-NC-NC
UCC2895DW	ACTIVE	SOIC	DW	20	25	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UCC2895DWTR	ACTIVE	SOIC	DW	20	2000	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UCC2895N	ACTIVE	PDIP	N	20	20	TBD	CU NIPDAU	Level-NA-NA-NA
UCC2895PW	ACTIVE	TSSOP	PW	20	70	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UCC2895PWTR	ACTIVE	TSSOP	PW	20	2000	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UCC2895PWTRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC2895Q	ACTIVE	PLCC	FN	20	46	TBD	Call TI	Level-2-220C-1 YEAR
UCC2895QTR	ACTIVE	PLCC	FN	20	1000	TBD	Call TI	Level-2-220C-1 YEAR
UCC3895DW	ACTIVE	SOIC	DW	20	25	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UCC3895DWTR	ACTIVE	SOIC	DW	20	2000	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UCC3895DWTRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UCC3895N	ACTIVE	PDIP	N	20	20	TBD	CU NIPDAU	Level-NA-NA-NA
UCC3895PW	ACTIVE	TSSOP	PW	20	70	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UCC3895PWTR	ACTIVE	TSSOP	PW	20	2000	TBD	CU NIPDAU	Level-2-220C-1 YEAR
UCC3895PWTRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UCC3895Q	ACTIVE	PLCC	FN	20	46	TBD	Call TI	Level-2-220C-1 YEAR
UCC3895QTR	ACTIVE	PLCC	FN	20	1000	TBD	Call TI	Level-2-220C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



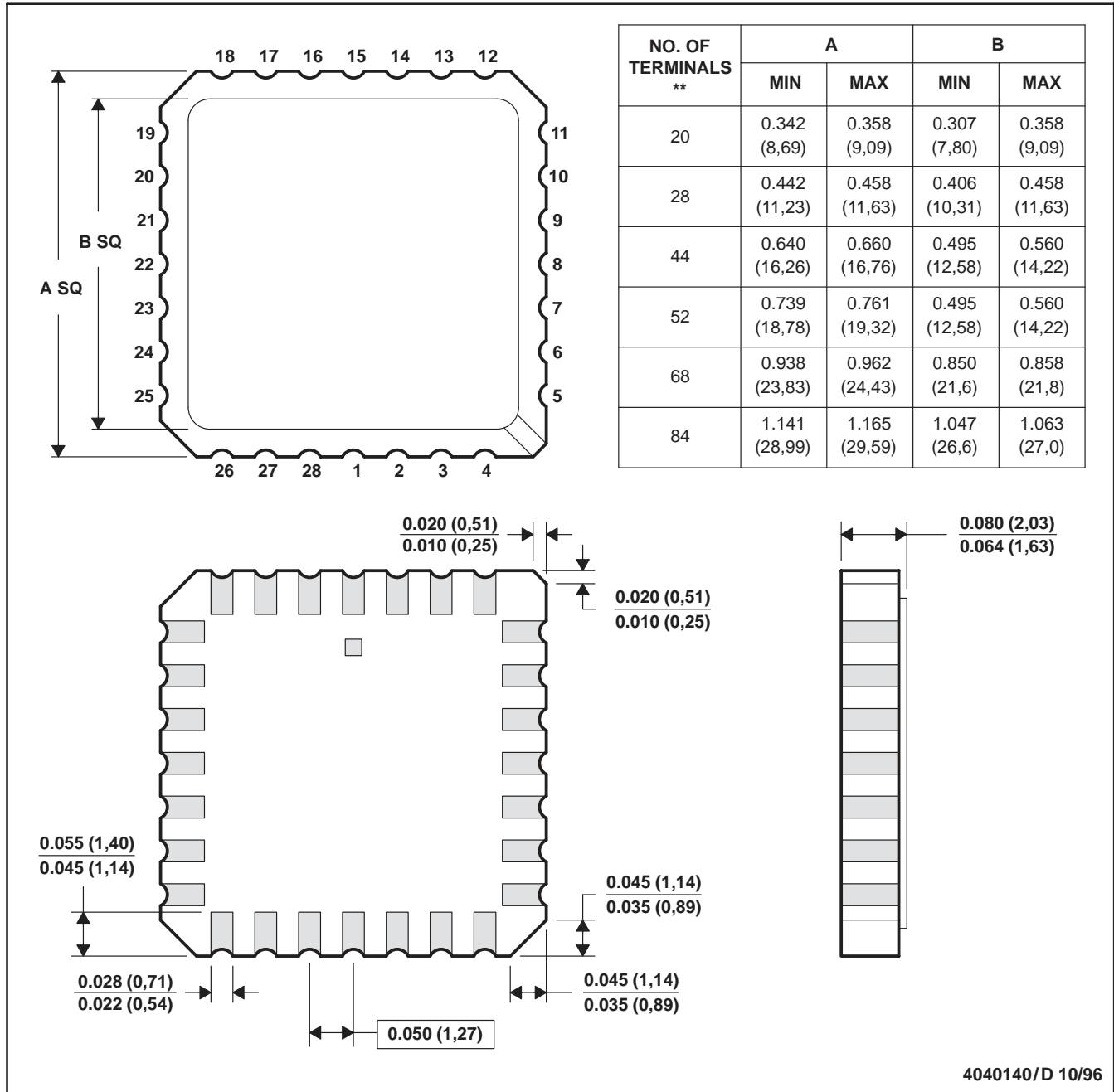
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

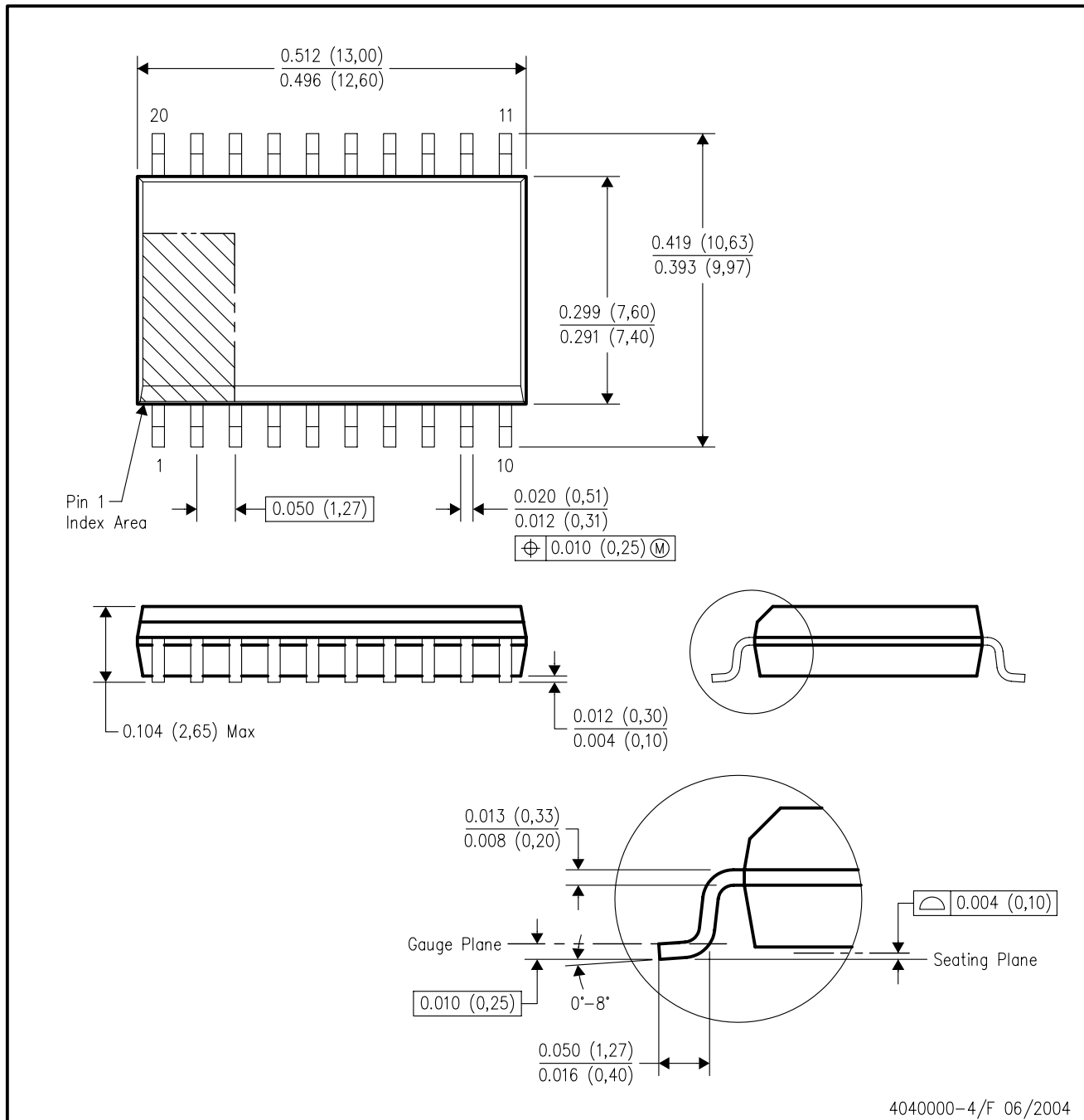
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE

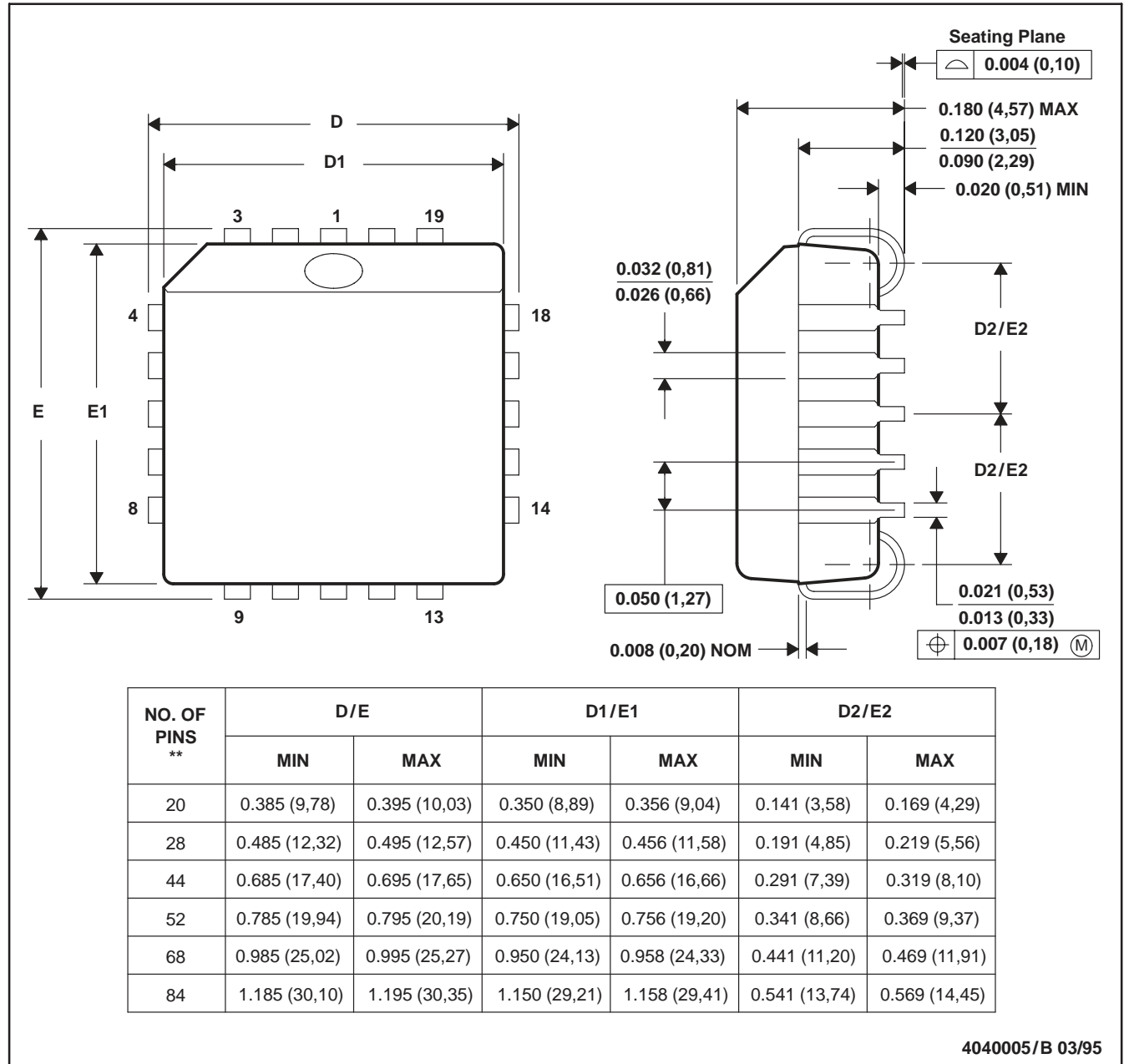


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

FN (S-PQCC-J**)

PLASTIC J-LEADED CHIP CARRIER

20 PIN SHOWN

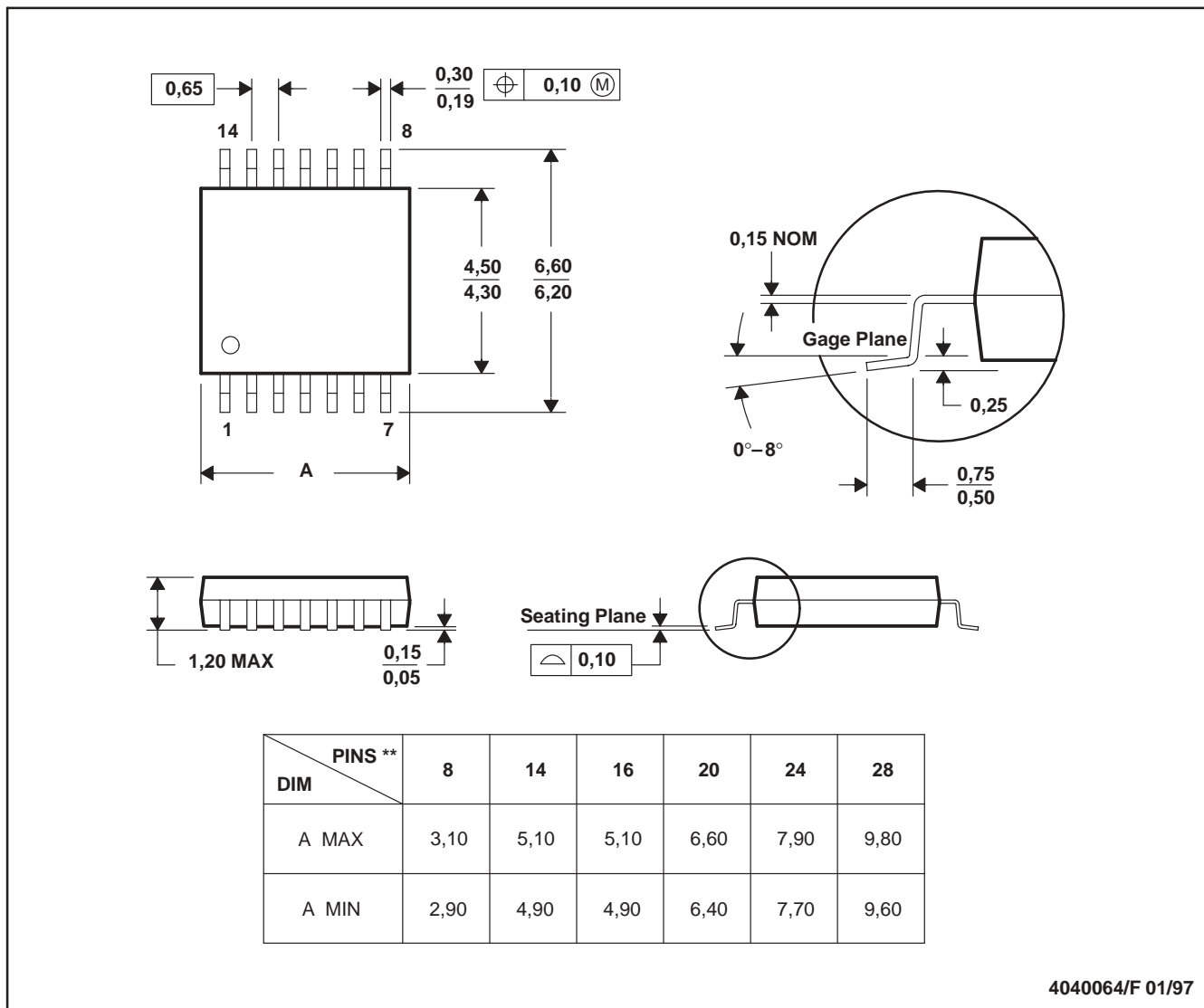


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-018

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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